

Product Change Notification / MFOL-31LDJJ524

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08-Sep-2022

Product Category:

LIN Transceiver with Vreg and Watchdog Timer

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5213 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for ATA663454-GDQW, ATA663431-GDQW, ATA663454-GDQW-VAO, and ATA663431-GDQW-VAO catalog part numbers (CPN) in 16L VQFN (3x5.5x1mm) package at ASCL assembly site.

Affected CPNs:

MFOL-31LDJJ524_Affected_CPN_09082022.pdf MFOL-31LDJJ524_Affected_CPN_09082022.csv

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for ATA663454-GDQW, ATA663431-GDQW, ATA663454-GDQW-VAO, and ATA663431-GDQW-VAO catalog part numbers (CPN) in 16L VQFN (3x5.5x1mm) package at ASCL

assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change		
	ASE Group Chung-Li	ASE Group Chung-Li		
Assembly Site				
	(ASCL)	(ASCL)		
Wire Material	PCC	CuPdAu		
Die Attach Material	EN-4900G	EN-4900G		
Molding Compound Material	G700LA	G700LA		
Lead-Frame Material	C7025	C7025		
Lead-Frame Paddle Size	1.9 x 5.1mm	1.9 x 5.1mm		
DAP Surface Prep	Selective Ag plating	Selective Ag plating		

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity and on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) bond wire and mold compound G700LA-HP at ASCL assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:November 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	September 2022					>	November 2022				2
Workweek	3 6	3 7	3 8	3 9	4 0		45	46	47	48	49
Initial PCN Issue Date		Х									

Qual Report Availability				Х		
Final PCN Issue				V		
Date				X		

Method to Identify Change:Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:September 08, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_MFOL-31LDJJ524_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

MFOL-31LDJJ524 - CCB 5213 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for ATA663454-GDQW, ATA663451-GDQW, ATA663454-GDQW-VAO, and ATA663431-GDQW-VAO catalog part numbers (CPN) in 16L VQFN (3x5.5x1mm) package at ASCL assembly site.

Affected Catalog Part Numbers (CPN)

ATA663454-GDQW ATA663451-GDQW-VAO ATA663451-GDQW-VAO